

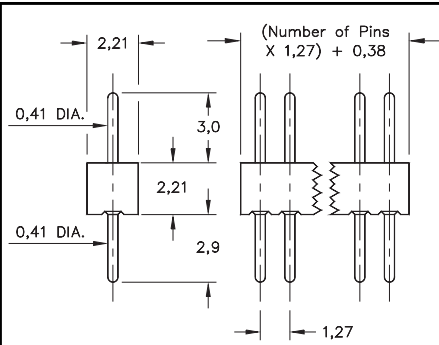


Fig. 1

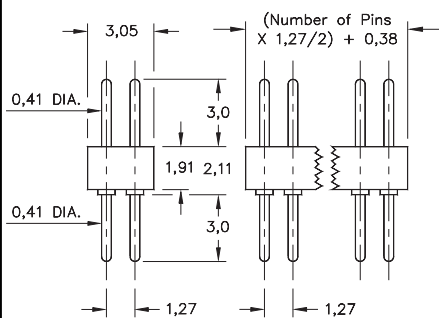


Fig. 2

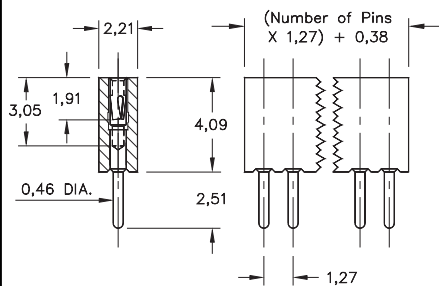


Fig. 3

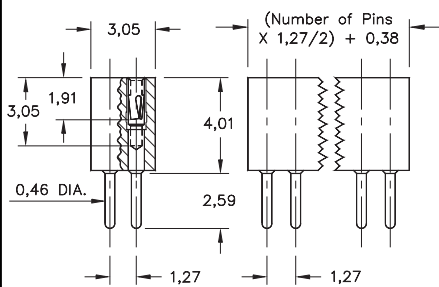


Fig. 4

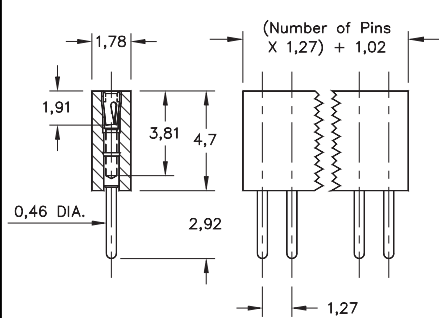
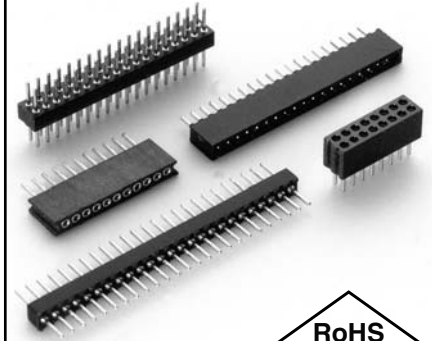


Fig. 5

- Series 850 single and double row interconnects have 1,27 pin spacing & permit board stacking as low as 6,3.
- Pin headers have 0,41 dia. pins (MM #4006-0). See page 175 for details.
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contacts rated at 3 amps. (#11 contact accepts pin diameters from 0,38 - 0,51). See pages 129 and 131 for details.
- Insulators are high temp. thermoplastic, suitable for all soldering operations.



Ordering Information

Fig. 1	Single Row	2,21 Profile Pin Header
	850-XX-0_-10-001000	Specify # of pins → 01-50
Fig. 2	Double Row	1,91 Profile Pin Header
	852-XX-_-10-001000	Specify # of pins → 002-100

For Electrical, Mechanical & Environmental Data, See pg. 4

XX=Plating Code See Below

For RoHS compliance select ◇ plating code.

SPECIFY PLATING CODE XX=	10◇	90	40◇	
Pin Plating	0,25μm Au	5,08μm Sn/Pb	5,08μm Sn	

Fig. 3	Single Row	4,09 Profile Socket
	851-XX-0_-10-001000	Specify # of pins → 01-50
Fig. 4	Double Row	4,09 Profile Socket
	853-XX-_-10-001000	Specify # of pins → 002-100
Fig. 5	Single Row	4,7 Profile Socket
	851-XX-0_-10-002000	Specify # of pins → 01-77

For Electrical, Mechanical & Environmental Data, See pg. 4

XX=Plating Code See Below

For RoHS compliance select ◇ plating code.

SPECIFY PLATING CODE XX=		93	99		43◇	
Sleeve (Pin)		5,08μm Sn/Pb	5,08μm Sn/Pb		5,08μm Sn	
Contact (Clip)		0,76μm Au	5,08μm Sn/Pb		0,76μm Au	